



Material Content Data Sheet



Sales Product Name		ESD101-B1-02EL E6327		Issued		19. January 2018		
MA#		MA001612064						
Package		PG-TSLP-2-20		Weight*		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.11		1135	
	noble metal	gold	7440-57-5	0.003	0.44		4404	
	inorganic material	silicon	7440-21-3	0.022	3.57	4.12	35706	41245
leadframe	non noble metal	nickel	7440-02-0	0.241	39.17	39.17	391710	391710
wire	noble metal	gold	7440-57-5	0.007	1.09	1.09	10944	10944
encapsulation	organic material	carbon black	1333-86-4	0.002	0.26		2584	
	plastics	epoxy resin	-	0.046	7.50		74950	
	inorganic material	silicondioxide	60676-86-0	0.270	43.93	51.69	439367	516901
leadfinish	noble metal	gold	7440-57-5	0.010	1.70	1.70	16962	16962
plating	noble metal	palladium	7440-05-3	0.003	0.53		5276	
	noble metal	gold	7440-57-5	0.010	1.70	2.23	16962	22238
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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